

The background of the slide is a high-resolution, colorful microchip die. The die is composed of various colored regions: a large orange-red area at the top, a yellow-green area in the middle, and a blue area at the bottom. The die is set against a black background. A large, light green arrow points from the top left towards the center of the die. A purple shape is in the bottom left, and a small green triangle is in the bottom right.

Singapore  
**HPC Advisory Council**

October 7<sup>th</sup> 2014

**AMD GPU COMPUTING**

JC BARATAULT

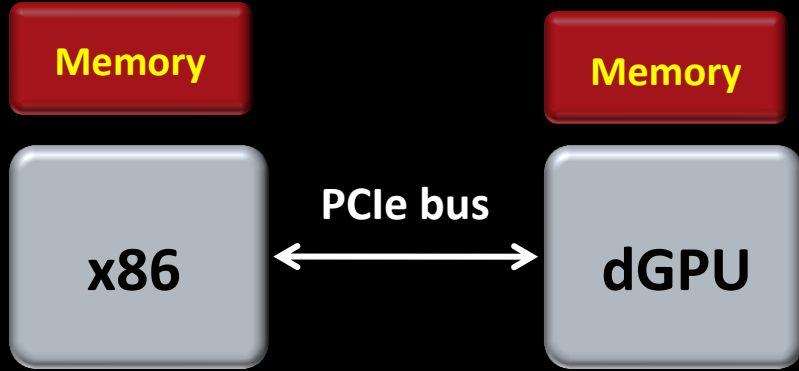
[JC.BARATAULT@AMD.COM](mailto:JC.BARATAULT@AMD.COM)

GLOBAL GPU COMPUTING

**1 EXAFLOPS**

**20 MW**

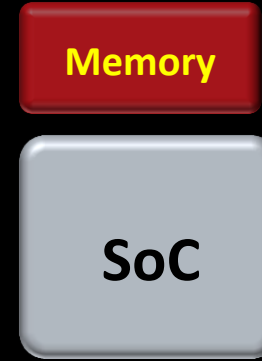
**50 GFLOPS DP/W**



## DATA TO WORK

Since 2007

Not efficient!



## WORK TO DATA

Beyond 2015

Run indifferently serial and parallel codes

# WHY AMD



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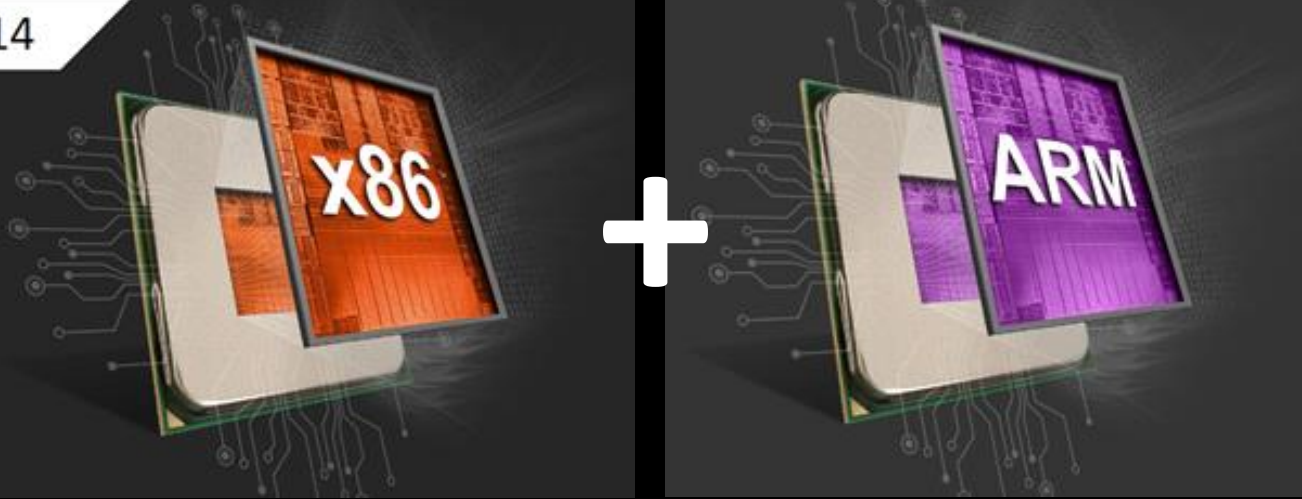
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ARM

# Ambidextrous Computing

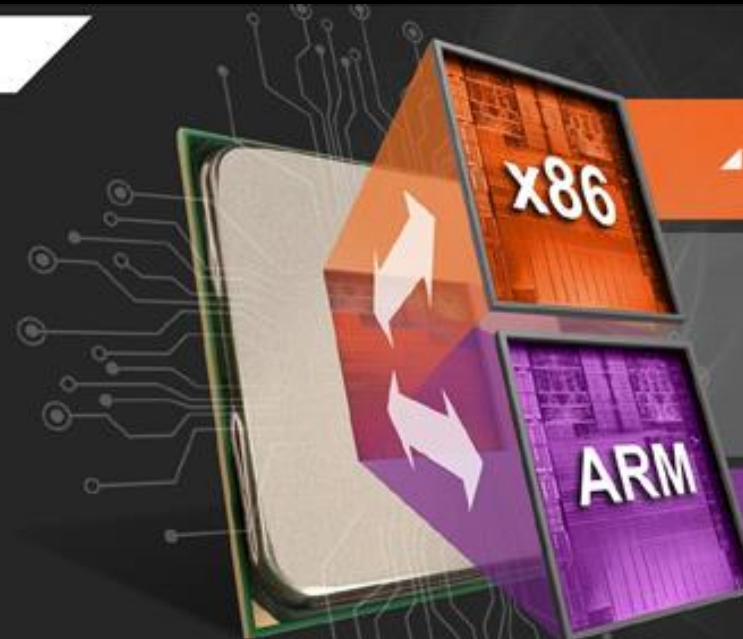


2014



HSA compliant & Lower power APU    28nm 64-bit ARM server processor

2015



▲ Next-Gen "Puma+" x86 Cores

- ▲ Starting in 2015, families of 20nm APUs and SoCs with pin-compatible x86/ARM compute
- ▲ Designed for Full HSA support
- ▲ AMD Graphics Core Next (GCN)

- ▲ Low-power A57 64-bit ARM Cores
- ▲ AMD's first HSA Android platform

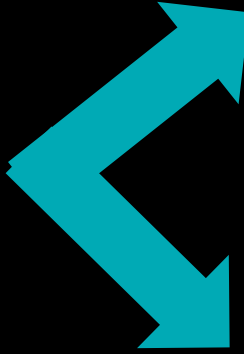
# AMD FIREPRO

# AMD FirePro Professional Graphics



Professional GPUs  
OpenGL + OpenCL

All PCIe Gen3



Workstations



Datacenters



Active cooling



Passive cooling



GPU Computing



VDI & Cloud



**FirePro S9150**

**16 GB**

**2 TF DGEMM**



**ADVANTECH**  
*Enabling an Intelligent Planet*

**ASUS**<sup>®</sup>  
Rock Solid · Heart Touching

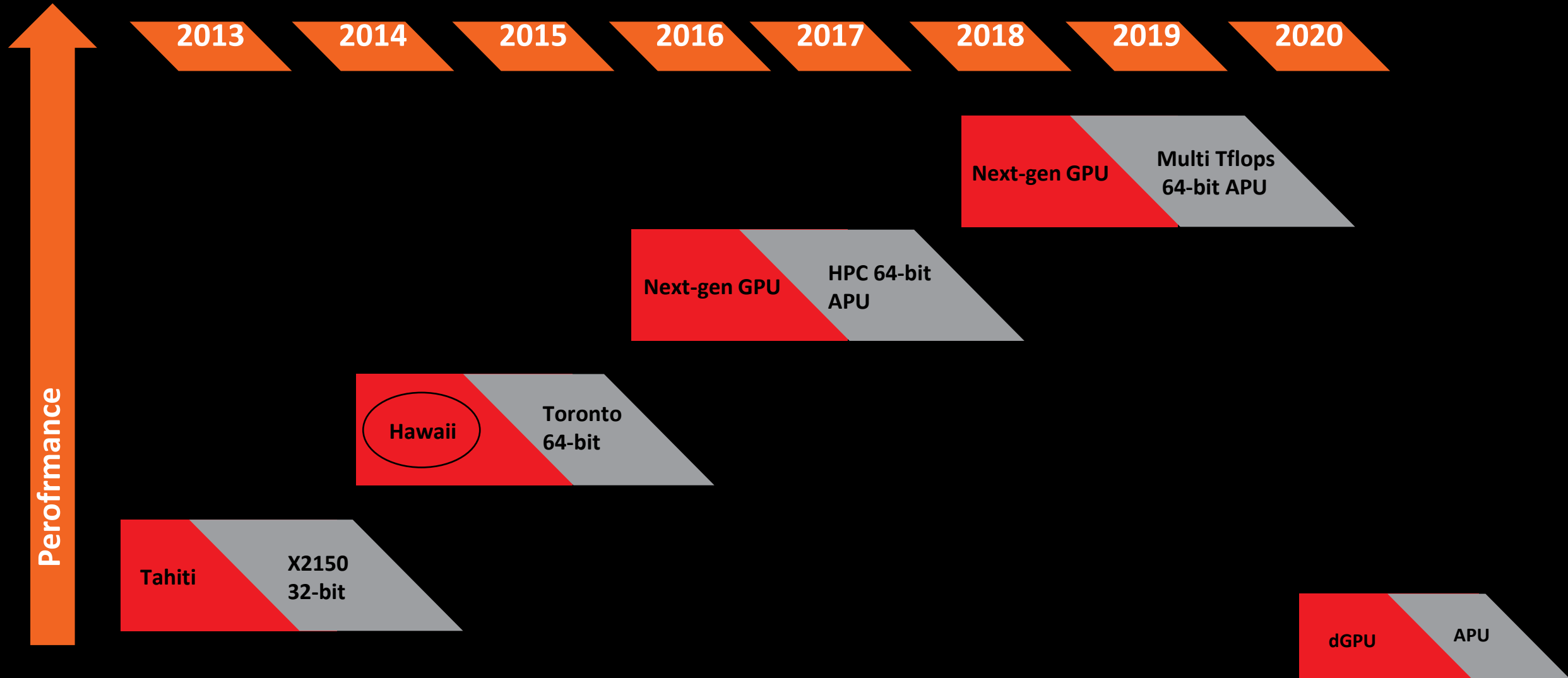
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**GIGABYTE**<sup>™</sup>  
TECHNOLOGY

**SUPERMICR**<sup>®</sup>

**TYAN**

# We have plans for the coming 10 years



# Smooth and Efficient Transition from dGPU to SoC



FirePro  
Graphics



APU



Server  
CPU



# LEGACY CODES

## From dGPU to SoC

**Need for open programming framework  
for legacy and future-proof codes**

# Heterogeneous System Architecture

Write-once-run-everywhere for heterogeneous systems



Key Founders of the HSA Foundation

# HSA Foundation



Write-once-run-everywhere for heterogeneous systems

- ▲ Industry leaders setting an industry standard
- ▲ Designed for developers, by developers
- ▲ One architecture, differentiated 'IP' vendors
  - Multiple hardware solutions to be exposed to software through a common standard low-level interface layer
- ▲ Support high-level parallel programming languages and models, including C++ AMP, C++, C#, FORTRAN, **OpenCL**, **OpenMP**, Java and Python



# DIVERSE PARTNERS DRIVING FUTURE OF HETEROGENEOUS COMPUTING



## Founders



## Promoters



## Supporters



## Contributors



## Academic



# OpenCL 2.0

### ▲ Focus on HSA and HSA-like devices

- GPU and CPU are capable of sharing memory, pointers, cache, and more
- OpenCL 1.x is already capable of running on these devices, but it lacks effective means to take advantage of the interconnected hardware, which is where OpenCL 2.0's additions come in

### ▲ Shared Virtual Memory

- Host and device kernels can directly share complex and pointer containing data structures eliminating costly data transfer between host and devices

### ▲ Dynamic Parallelism

- Device kernels can enqueue kernels to the same device without host interaction

### ▲ Generic Address Space

- Functions can be written without specifying a named address space for arguments



## ▲ AMD

- OpenCL 1.2 today
- OpenCL 2.0 Q4 2014

## ▲ INTEL

- OpenCL 1.2 today
- OpenCL 2.0 Q3 2014 (CPU)

## ▲ ALTERA


- OpenCL on FPGA

## ▲ MICROSOFT

- OpenCL 'Windows Server 2015'

## ▲ APPLE

- 100% OpenCL



# Be locked or be free



## OpenCL

AMD FirePro S-Series is the only graphics processor that supports a cross-vendor GPU code program on OpenCL 1.2. Programmers can make a single program when developing code by targeting multi-vendor CPUs, multi-vendor GPUs and discrete GPUs, freeing themselves from vendor-specific programming.

Find out more @ [www.amd.com](http://www.amd.com)

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# OpenMP 4.0

“Pathscale’s ENZO Compiler with OpenMP 4.0 and support for C, C++, and Fortran is used by customers in the Oil and Gas, Computational Science, Computer Aided Engineering, and other HPC segments.

Our support for the AMD FirePro S9150 will enable these customers to benefit from the tremendous compute performance of the S9150 while leveraging their existing investment in OpenMP software.”

Christopher Bergstrom, CTO, PathScale



## Support for OpenMP 4.0 & OpenACC 1.0

- ▲ Full OpenMP 4.0 implementation
- ▲ OpenACC 1.0 all Hawaii and Tahiti-based FirePro cards with C, C++, Fortran
  - FirePro S-series: S10000, S9150/S9100, S9050/S9000
  - FirePro W-series: W9100, W9000, W8100, W8000
- ▲ November 2014 Beta
- ▲ December 2014 Production release





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- ✓ Open software stacks
- ✓ Users not locked in
- ✓ Future proof solutions



# Thank you

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